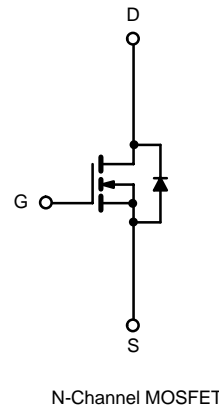
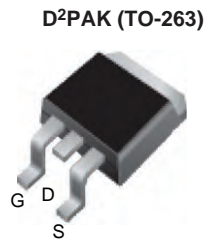


## N-Channel 100 V (D-S) 175 °C MOSFET

| PRODUCT SUMMARY     |                                 |                    |
|---------------------|---------------------------------|--------------------|
| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω)         | I <sub>D</sub> (A) |
| 100                 | 0.004 at V <sub>GS</sub> = 10 V | 140 <sup>a</sup>   |

### FEATURES

- TrenchFET<sup>®</sup> Power MOSFET
- New Package with Low Thermal Resistance
- 100 % R<sub>g</sub> Tested



| ABSOLUTE MAXIMUM RATINGS T <sub>C</sub> = 25 °C, unless otherwise noted |                                   |                         |                  |
|---|-----------------------------------|-------------------------|------------------|
| Parameter   | Symbol                            | Limit                   | Unit             |
| Drain-Source Voltage  | V <sub>DS</sub>                   | 100                     | V                |
| Gate-Source Voltage   | V <sub>GS</sub>                   | ± 20                    |                  |
| Continuous Drain Current (T <sub>J</sub> = 175 °C)                      | I <sub>D</sub>                    | T <sub>C</sub> = 25 °C  | 140 <sup>a</sup> |
|   |                                   | T <sub>C</sub> = 125 °C | 87 <sup>a</sup>  |
| Pulsed Drain Current  | I <sub>DM</sub>                   | 440                     | A                |
| Avalanche Current   | I <sub>AR</sub>                   | 75                      |                  |
| Repetitive Avalanche Energy <sup>b</sup>                                | E <sub>AR</sub>                   | 280                     | mJ               |
| Maximum Power Dissipation <sup>b</sup>                                  | P <sub>D</sub>                    | T <sub>C</sub> = 25 °C  | 375 <sup>c</sup> |
|   |                                   | T <sub>A</sub> = 25 °C  | 3.75             |
| Operating Junction and Storage Temperature Range                        | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 175             | °C               |

| THERMAL RESISTANCE RATINGS |                   |       |      |
|----------------------------|-------------------|-------|------|
| Parameter                  | Symbol            | Limit | Unit |
| Junction-to-Ambient        | R <sub>thJA</sub> | 40    | °C/W |
| Junction-to-Case (Drain)   | R <sub>thJC</sub> | 0.4   |      |

Notes:

- Package limited.
- Duty cycle ≤ 1 %.
- See SOA curve for voltage derating.
- When mounted on 1" square PCB (FR-4 material).

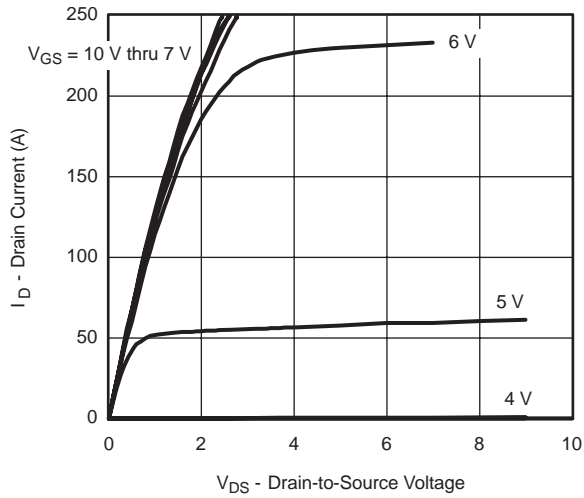
| <b>SPECIFICATIONS</b> $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted                     |               |  |      |       |           |               |
|---|---------------|--|------|-------|-----------|---------------|
| Parameter   | Symbol        | Test Conditions  | Min. | Typ.  | Max.      | Unit          |
| <b>Static</b>   |               |  |      |       |           |               |
| Drain-Source Breakdown Voltage  | $V_{DS}$      | $V_{DS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$  | 100  |       |           | V             |
| Gate-Threshold Voltage  | $V_{GS(th)}$  | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$  | 2    |       | 4         |               |
| Gate-Body Leakage   | $I_{GSS}$     | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$  |      |       | $\pm 100$ | nA            |
| Zero Gate Voltage Drain Current   | $I_{DSS}$     | $V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}$   |      |       | 1         | $\mu\text{A}$ |
|   |               | $V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$  |      |       | 50        |               |
|   |               | $V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}, T_J = 175\text{ }^\circ\text{C}$  |      |       | 250       |               |
| On-State Drain Current <sup>a</sup>   | $I_{D(on)}$   | $V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$   | 120  |       |           | A             |
| Drain-Source On-State Resistance <sup>a</sup>   | $R_{DS(on)}$  | $V_{GS} = 10\text{ V}, I_D = 30\text{ A}$  |      | 0.004 |           | $\Omega$      |
|   |               | $V_{GS} = 10\text{ V}, I_D = 30\text{ A}, T_J = 125\text{ }^\circ\text{C}$   |      | 0.017 |           |               |
|   |               | $V_{GS} = 10\text{ V}, I_D = 30\text{ A}, T_J = 175\text{ }^\circ\text{C}$   |      | 0.025 |           |               |
| Forward Transconductance <sup>a</sup>   | $g_{fs}$      | $V_{DS} = 15\text{ V}, I_D = 30\text{ A}$  | 25   |       |           | S             |
| <b>Dynamic<sup>b</sup></b>  |               |  |      |       |           |               |
| Input Capacitance   | $C_{iss}$     | $V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$  |      | 5500  |           | $\mu\text{F}$ |
| Output Capacitance  | $C_{oss}$     |  |      | 750   |           |               |
| Reverse Transfer Capacitance  | $C_{rss}$     |  |      | 280   |           |               |
| Total Gate Charge <sup>c</sup>  | $Q_g$         | $V_{DS} = 50\text{ V}, V_{GS} = 10\text{ V}, I_D = 85\text{ A}$  |      | 110   | 160       | nC            |
| Gate-Source Charge <sup>c</sup>   | $Q_{gs}$      |  |      | 24    |           |               |
| Gate-Drain Charge <sup>c</sup>  | $Q_{gd}$      |  |      | 24    |           |               |
| Gate Resistance   | $R_g$         |  | 1.0  |       | 6.2       | $\Omega$      |
| Turn-On Delay Time <sup>c</sup>   | $t_{d(on)}$   | $V_{DD} = 50\text{ V}, R_L = 0.6\text{ }\Omega$<br>$I_D \cong 85\text{ A}, V_{GEN} = 10\text{ V}, R_g = 2.5\text{ }\Omega$ |      | 20    | 30        | ns            |
| Rise Time <sup>c</sup>  | $t_r$         |  |      | 125   | 200       |               |
| Turn-Off Delay Time <sup>c</sup>  | $t_{d(off)}$  |  |      | 55    | 85        |               |
| Fall Time <sup>c</sup>  | $t_f$         |  |      | 130   | 195       |               |
| <b>Source-Drain Diode Ratings and Characteristics</b> $T_C = 25\text{ }^\circ\text{C}$ <sup>b</sup> |               |  |      |       |           |               |
| Continuous Current  | $I_S$         |  |      |       | 140       | A             |
| Pulsed Current  | $I_{SM}$      |  |      |       | 240       |               |
| Forward Voltage <sup>a</sup>  | $V_{SD}$      | $I_F = 85\text{ A}, V_{GS} = 0\text{ V}$   |      | 1.0   | 1.5       | V             |
| Reverse Recovery Time   | $t_{rr}$      | $I_F = 50\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$  |      | 70    | 140       | ns            |
| Peak Reverse Recovery Charge  | $I_{RM(REC)}$ |  |      | 5.5   | 10        | A             |
| Reverse Recovery Charge   | $Q_{rr}$      |  |      | 0.19  | 0.35      | $\mu\text{C}$ |

## Notes:

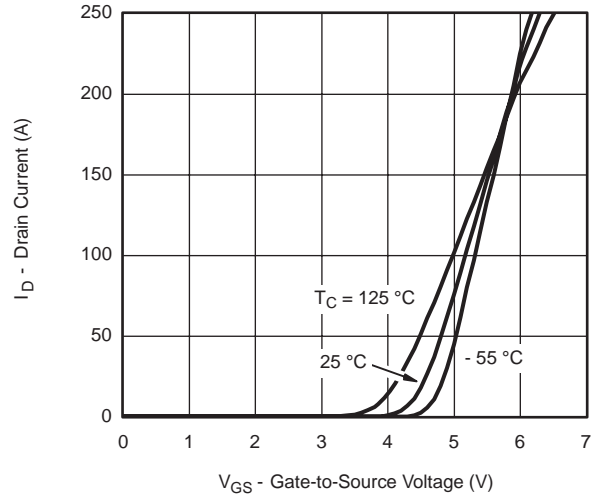
- Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

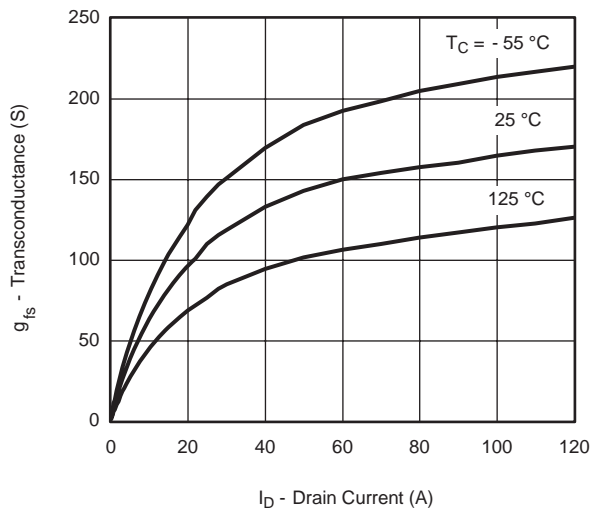
**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



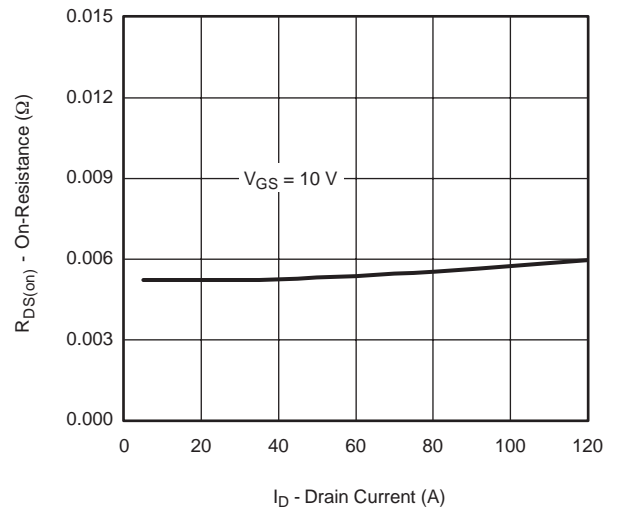
$V_{DS}$  - Drain-to-Source Voltage  
**Output Characteristics**



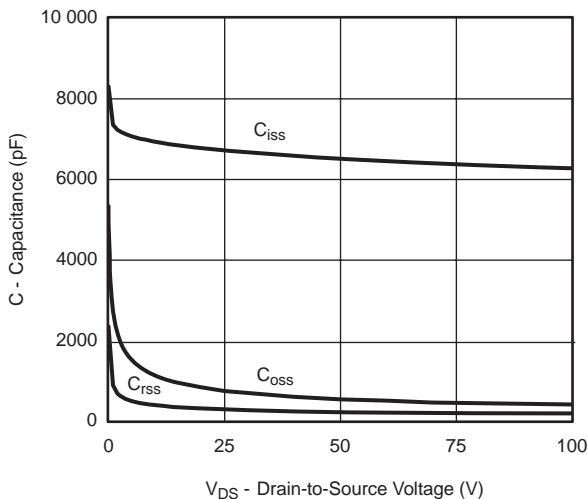
$V_{GS}$  - Gate-to-Source Voltage (V)  
**Transfer Characteristics**



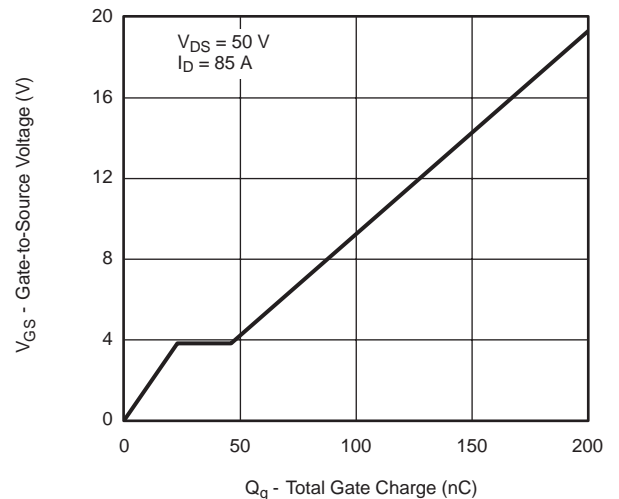
$I_D$  - Drain Current (A)  
**Transconductance**



$I_D$  - Drain Current (A)  
**On-Resistance vs. Drain Current**

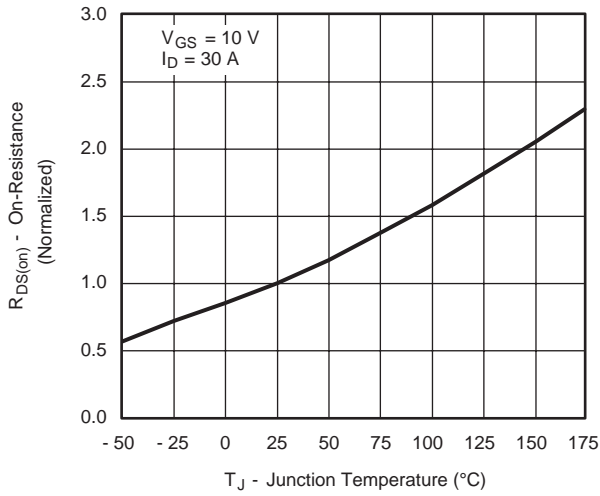


$V_{DS}$  - Drain-to-Source Voltage (V)  
**Capacitance**

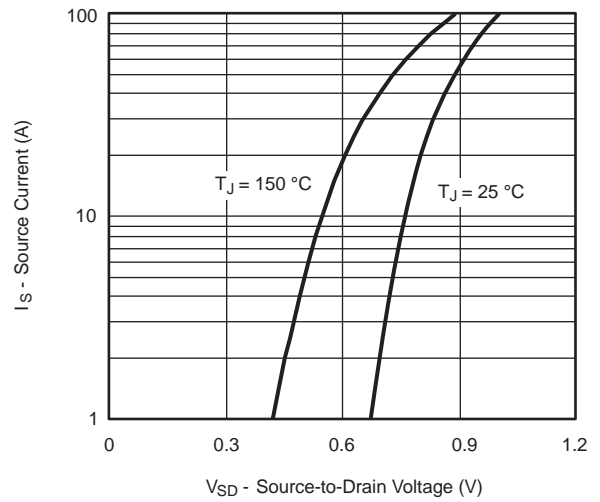


$Q_g$  - Total Gate Charge (nC)  
**Gate Charge**

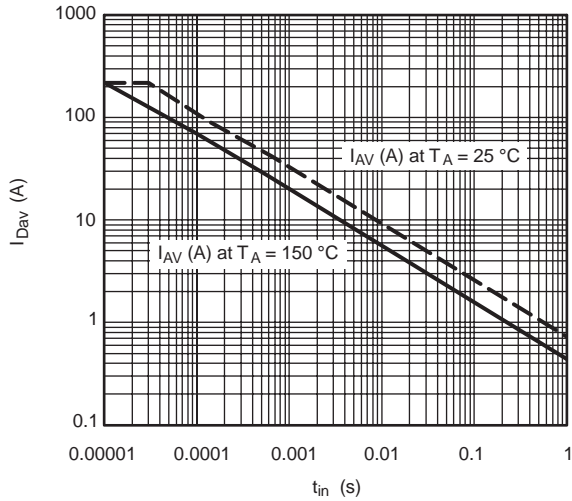
**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



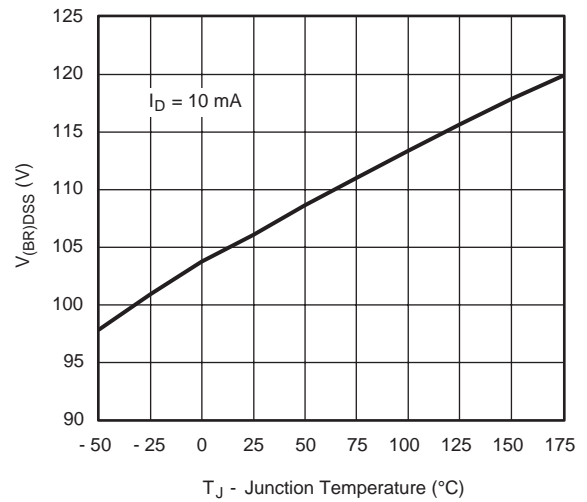
**On-Resistance vs. Junction Temperature**



**Source-Drain Diode Forward Voltage**

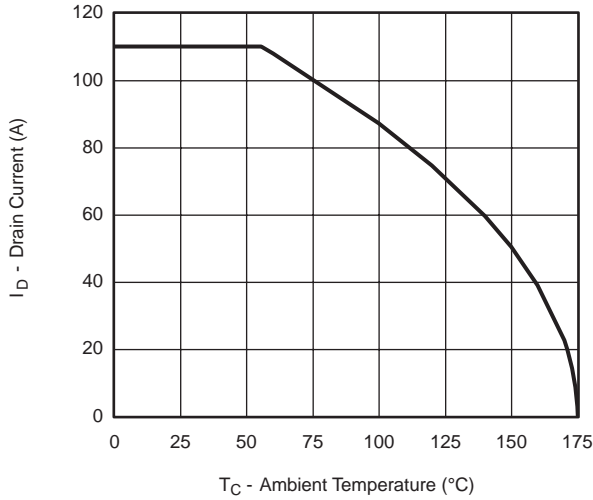


**Avalanche Current vs. Time**

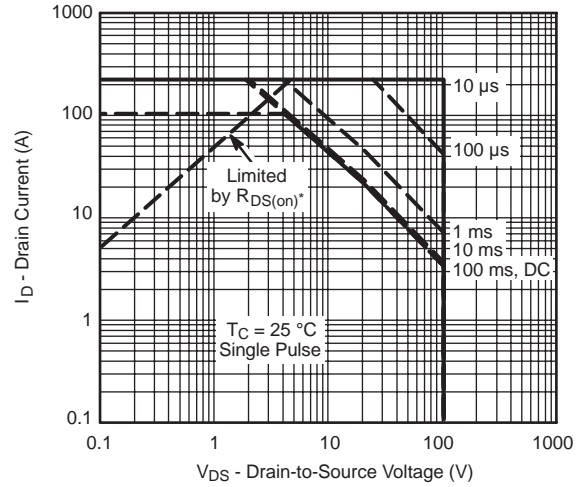


**Drain Source Breakdown vs. Junction Temperature**

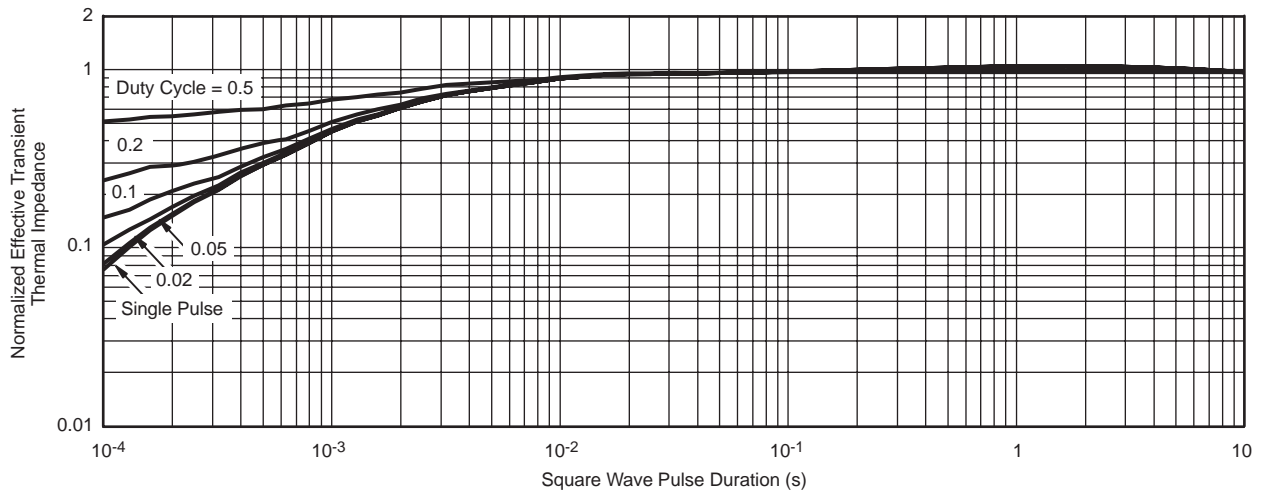
**THERMAL RATINGS**



**Maximum Avalanche and Drain Current vs. Case Temperature**

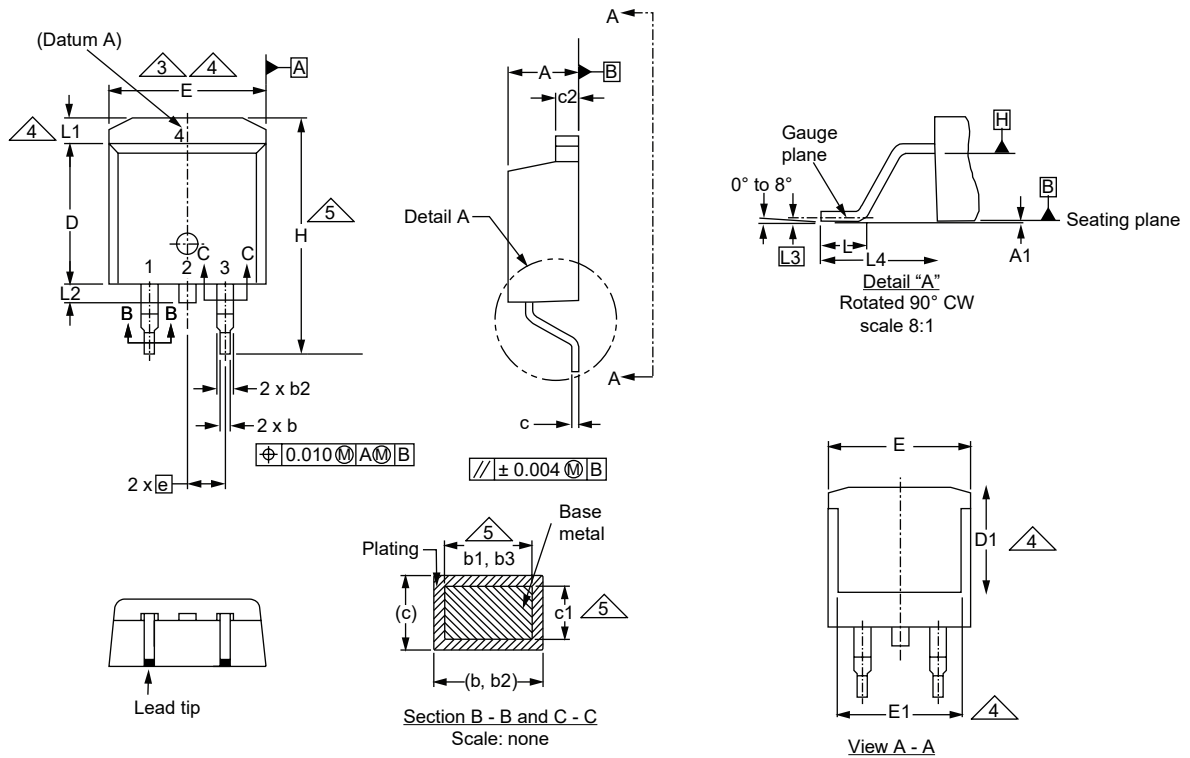


**Safe Operating Area**  
\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified



**Normalized Thermal Transient Impedance, Junction-to-Case**

TO-263AB (HIGH VOLTAGE)



| DIM. | MILLIMETERS |      | INCHES |       |
|------|-------------|------|--------|-------|
|      | MIN.        | MAX. | MIN.   | MAX.  |
| A    | 4.06        | 4.83 | 0.160  | 0.190 |
| A1   | 0.00        | 0.25 | 0.000  | 0.010 |
| b    | 0.51        | 0.99 | 0.020  | 0.039 |
| b1   | 0.51        | 0.89 | 0.020  | 0.035 |
| b2   | 1.14        | 1.78 | 0.045  | 0.070 |
| b3   | 1.14        | 1.73 | 0.045  | 0.068 |
| c    | 0.38        | 0.74 | 0.015  | 0.029 |
| c1   | 0.38        | 0.58 | 0.015  | 0.023 |
| c2   | 1.14        | 1.65 | 0.045  | 0.065 |
| D    | 8.38        | 9.65 | 0.330  | 0.380 |

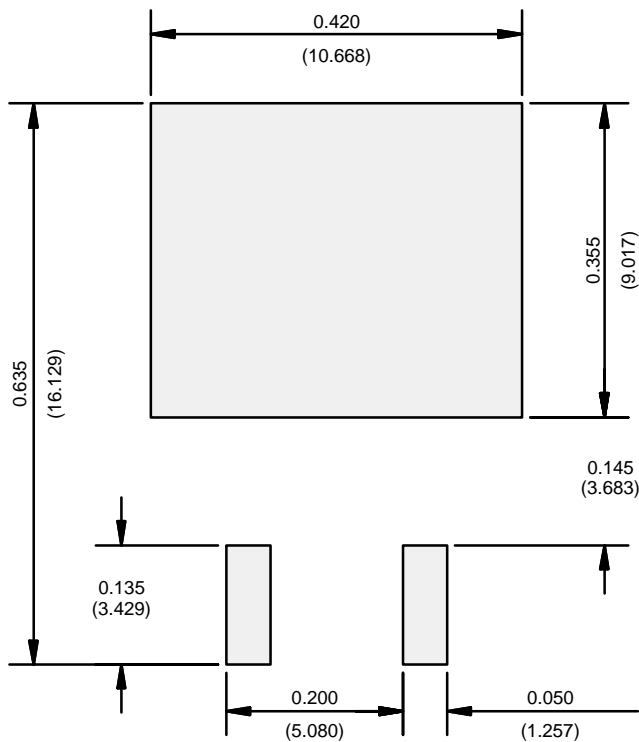
| DIM. | MILLIMETERS |       | INCHES    |       |
|------|-------------|-------|-----------|-------|
|      | MIN.        | MAX.  | MIN.      | MAX.  |
| D1   | 6.86        | -     | 0.270     | -     |
| E    | 9.65        | 10.67 | 0.380     | 0.420 |
| E1   | 6.22        | -     | 0.245     | -     |
| e    | 2.54 BSC    |       | 0.100 BSC |       |
| H    | 14.61       | 15.88 | 0.575     | 0.625 |
| L    | 1.78        | 2.79  | 0.070     | 0.110 |
| L1   | -           | 1.65  | -         | 0.066 |
| L2   | -           | 1.78  | -         | 0.070 |
| L3   | 0.25 BSC    |       | 0.010 BSC |       |
| L4   | 4.78        | 5.28  | 0.188     | 0.208 |

ECN: S-82110-Rev. A, 15-Sep-08  
DWG: 5970

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-2018.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.

**RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead**



Recommended Minimum Pads  
Dimensions in Inches/(mm)

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